

DIGITRON SEMICONDUCTORS

MR2000 SERIES

MEDIUM CURRENT SILICON RECTIFIERS

MAXIMUM RATINGS

Ratings	Symbol	MR 2000	MR 2001	MR 2002	MR 2004	MR 2006	MR 2008	MR 2010	Unit
Peak repetitive reverse voltage	V_{RRM}								
Working peak reverse voltage	V_{RWM}	50	100	200	400	600	800	1000	Volts
DC blocking voltage	V_R								
Non-repetitive peak reverse voltage (half-wave, single phase, 60Hz peak)	V_{RSM}	60	120	240	480	720	960	1200	Volts
RMS forward current	$I_{(RMS)}$	40							Amps
Average rectified forward current (single phase, resistive load, 60Hz, $T_C = 150^\circ\text{C}$)	I_O	20							Amps
Non-repetitive peak surge current (surge applied @ rated load conditions, half wave, single phase, 60Hz)	I_{FSM}	400(1 cycle)							Amps
Operating and storage temperature range	T_J, T_{stg}	-65 to +175							$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Thermal resistance, junction to case	$R_{\theta JC}$	1.3	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Maximum instantaneous forward voltage ($I_F = 63\text{A}, T_C = 25^\circ\text{C}$)	V_F	1.1	Volts
Maximum reverse current (rated dc voltage) $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_R	100 500	μA

FIGURE 1 – FORWARD VOLTAGE

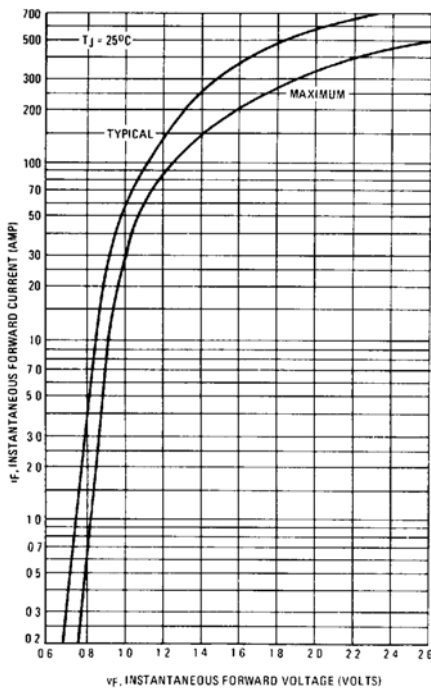
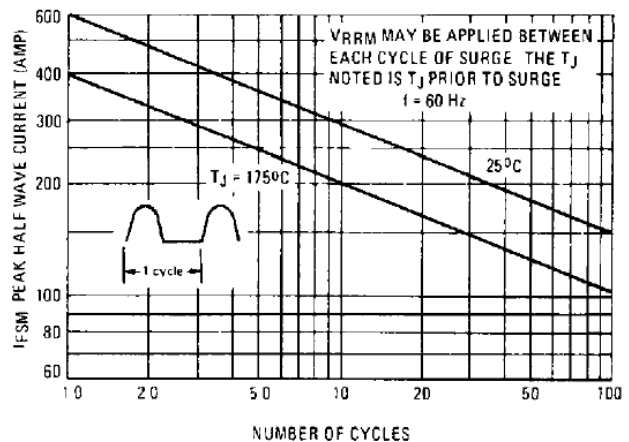


FIGURE 2 – NON-REPETITIVE SURGE CURRENT



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FIGURE 3 – FORWARD VOLTAGE TEMPERATURE COEFFICIENT

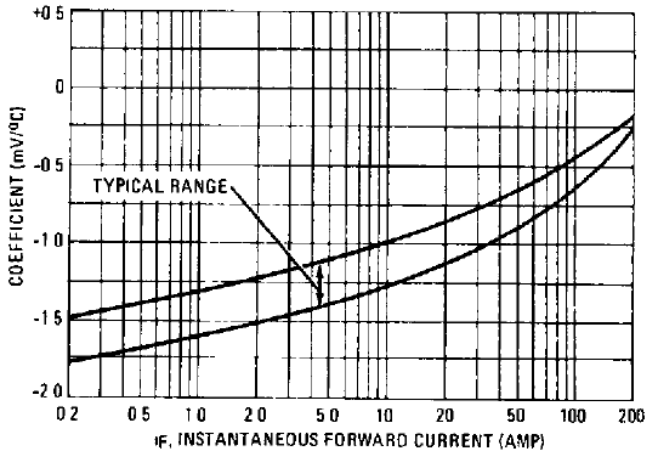


FIGURE 4 – CURRENT DERATING

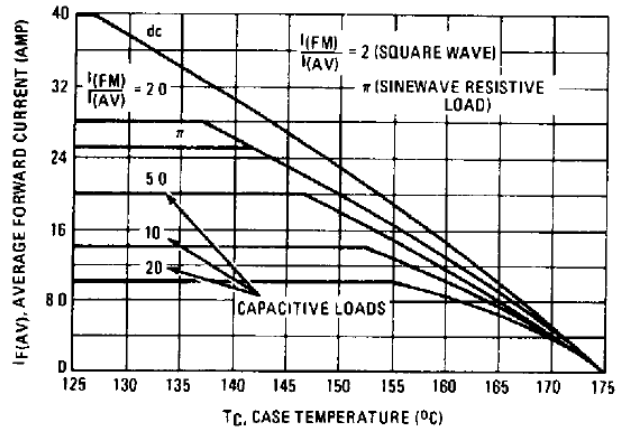


FIGURE 5 – FORWARD POWER DISSIPATION

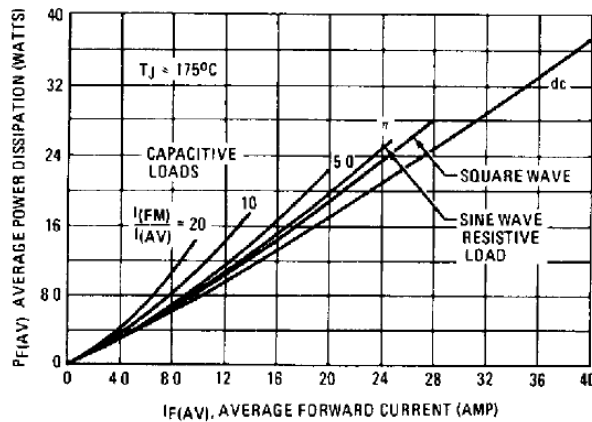
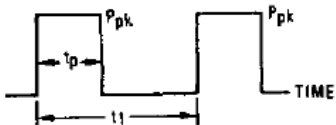
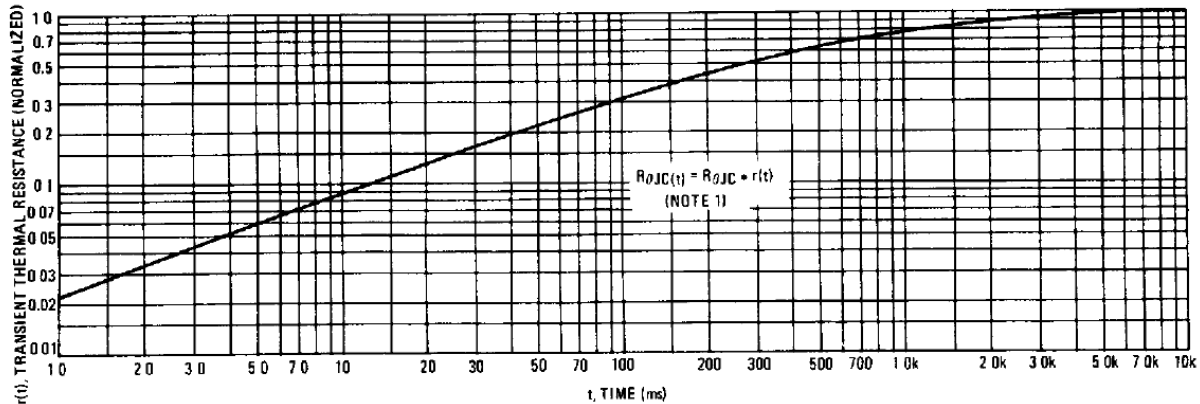


FIGURE 6 – THERMAL RESPONSE



Duty cycle = $D = t_p/t_1$
 Peak power = P_{pk}
 is peak of an equivalent square power pulse

To determine maximum junction temperature of the diode in a given situation the following procedure is recommended: The temperature of the case should be measured using a thermocouple placed on the case at the temperature reference point. The thermal mass connected to the case is normally large enough so that it will not significantly respond to heat surges generated in the diode as a result of pulsed operation once steady state conditions are achieved. Using the measured value of T_c the junction temperature may be determined by: $T_j = T_c + \Delta T_{JC}$, where ΔT_{JC} is the increase in junction temperature above the case temperature. It may be determined by $\Delta T_{JC} = P_{pk} \cdot R_{\theta JC} [D + (1-D) \cdot r(t_p + t_1) - r(t_1)]$ where $r(t)$ = normalized value of transient thermal resistance at time t from figure 6, and $r(t_1 + t_p)$ = normalized value of transient thermal resistance at time $t_1 + t_p$.

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FIGURE 7 – CAPACITANCE

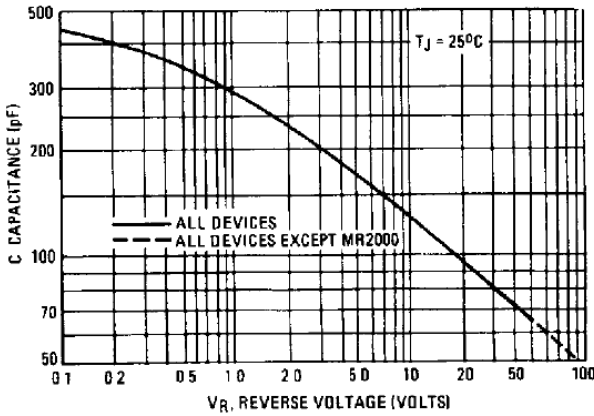


FIGURE 8 – FORWARD RECOVERY TIME

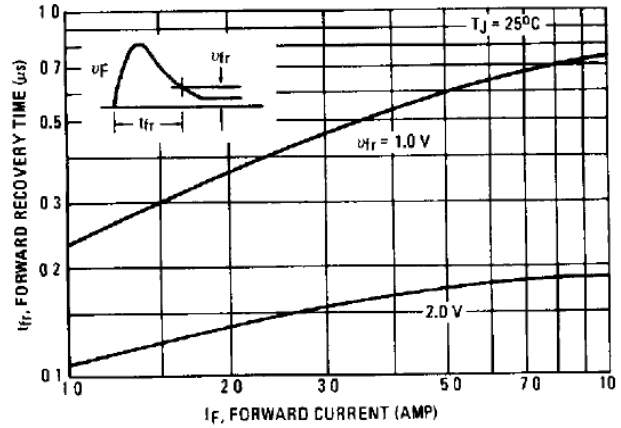


FIGURE 9 – REVERSE RECOVERY TIME

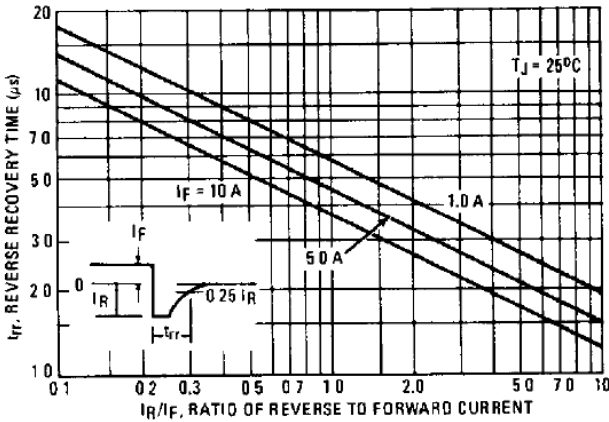


FIGURE 10 – RECTIFICATION WAVEFORM EFFICIENCY

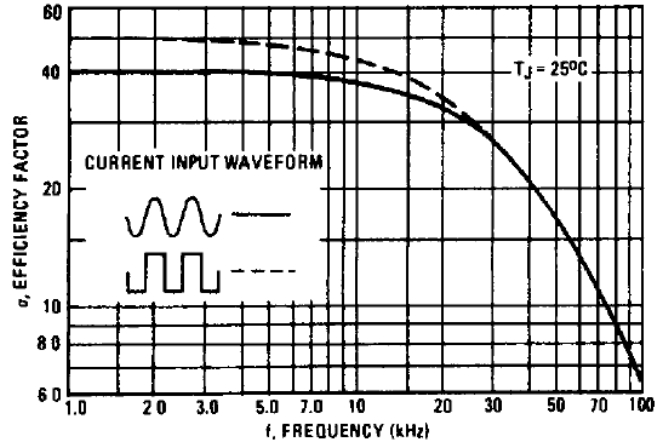
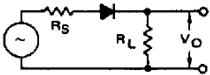


FIGURE 11 – SINGLE-PHASE HALF-WAVE RECTIFIER CIRCUIT



The rectification efficiency factor σ shown in Figure 10 was calculated using the formula:

$$\sigma = \frac{P_{dc}}{P_{rms}} = \frac{\frac{V_o^2(dc)}{R_L}}{\frac{V_o^2(rms)}{R_L}} \cdot 100\% = \frac{V_o^2(dc)}{V_o^2(ac) + V_o^2(dc)} \cdot 100\% \quad (1)$$

For a sine wave input $V_m \sin(\omega t)$ to the diode, assume lossless, the maximum theoretical efficiency factor becomes

$$\sigma(\text{sine}) = \frac{\frac{V_m^2}{\pi^2 R_L}}{\frac{V_m^2}{4 R_L}} \cdot 100\% = \frac{4}{\pi^2} \cdot 100\% = 40.6\% \quad (2)$$

For a square wave input of amplitude V_m , the efficiency factor becomes:

$$\sigma(\text{square}) = \frac{\frac{V_m^2}{2 R_L}}{\frac{V_m^2}{R_L}} \cdot 100\% = 50\% \quad (3)$$

(A full wave circuit has twice these efficiencies)

As the frequency of the input signal is increased, the reverse recovery time of the diode (figure 9) becomes significant, resulting in an increasing ac voltage component across R_L which is opposite in polarity to the forward current, thereby reducing the value of the efficiency factor, σ , as shown in figure 10.

It should be emphasized that figure 10 shows waveform efficiency only; it does not provide a measure of diode losses. Data was obtained by measuring the ac component of V_o with a true rms ac voltmeter and the dc component with a dc voltmeter. The data was used in Equation 1 to obtain points for figure 10.

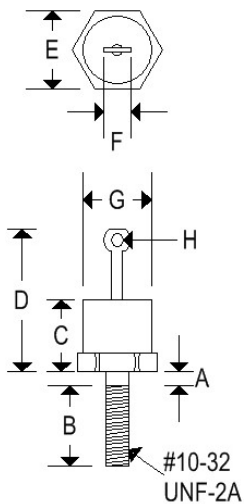
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MECHANICAL CHARACTERISTICS

Case	DO-4(R)
Marking	Alpha-numeric
Normal polarity	Cathode is stud
Reverse polarity	Anode is stud (add "R" suffix)



	DO-4(R)			
	Inches		Millimeters	
	Min	Max	Min	Max
A	-	0.078	-	1.981
B	0.422	0.453	10.719	11.506
C	-	0.405	-	10.287
D	-	0.800	-	20.320
E	0.420	0.440	10.668	11.176
F	-	0.250	-	6.350
G	-	0.424	-	10.770
H	0.066	-	1.676	-

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix).

Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.